

AUF1010ZL-VB Datasheet N-Channel 60 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	60				
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.006				
I _D (A)	120				
Configuration	Single				
Package	TO-262				

FEATURES

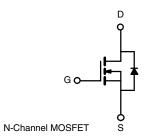
- TrenchFET® power MOSFET
- Package with low thermal resistance
- AEC-Q101 qualified d
- \bullet 100 % R_g and UIS tested







Top View



ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V_{DS}	60	V	
Gate-Source Voltage		V_{GS}	± 20	V	
Continuous Drain Current	T _C = 25 °C ^a	1	120		
	T _C = 125 °C	I _D	80		
Continuous Source Current (Diode Conduction) ^a		I _S	120	Α	
Pulsed Drain Current ^b		I _{DM}	480		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	65		
Single Pulse Avalanche Energy	L = 0.1 IIII	E _{AS}	211	mJ	
Maximum Power Dissipation ^b	T _C = 25 °C	P _D	230	W	
	T _C = 125 °C	L,D	76	VV	
Operating Junction and Storage Temperature Range		T_J, T_stg	-55 to +175	°C	

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	LIMIT	UNIT		
Junction-to-Ambient	PCB Mount c	R_{thJA}	40	°C/W		
Junction-to-Case (Drain)		R_{thJC}	0.65	C/VV		

Notes

- a. Package limited.
- b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- c. When mounted on 1" square PCB (FR4 material).
- d. Parametric verification ongoing.



PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0, I_D = 250 \mu A$		60	-	-	.,
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		3.0	3.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		1	-	± 100	nA
		V _{GS} = 0 V	V _{DS} = 60 V	1	-	1	
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V	V _{DS} = 60 V, T _J = 125 °C	1	-	50	μΑ
		V _{GS} = 0 V	V _{DS} = 60 V, T _J = 175 °C	1	-	250	
On-State Drain Current ^a	I _{D(on)}	V _{GS} = 10 V	V _{DS} ≥ 5 V	120	-	-	Α
		V _{GS} = 10 V	I _D = 30 A	1	0.0060	1	
Drain-Source On-State Resistance a	R _{DS(on)}	V _{GS} = 10 V	I _D = 30 A, T _J = 125 °C	-	0.0104	-	Ω
		V _{GS} = 10 V	I _D = 30 A, T _J = 175 °C	-	0.0129	-	
Forward Transconductance b	9 _{fs}	V _{DS}	V _{DS} = 15 V, I _D = 30 A		94	-	S
Dynamic ^b							
Input Capacitance	C _{iss}			-	5196	6495	
Output Capacitance	C _{oss}	$V_{GS} = 0 V$	$V_{DS} = 25 \text{ V, f} = 1 \text{ MHz}$	-	708	885	pF
Reverse Transfer Capacitance	C _{rss}			-	336	420	
Total Gate Charge ^c	Qg			-	96.5	145	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$V_{DS} = 30 \text{ V}, I_{D} = 75 \text{ A}$	-	24.6	-	nC
Gate-Drain Charge ^c	Q_{gd}			-	27.2	-	
Gate Resistance	R_g	f = 1 MHz		0.3	1	1.7	Ω
Turn-On Delay Time ^c	t _{d(on)}				16	24	
Rise Time ^c	t _r	$V_{DD} = 30 \text{ V}, \text{ R}_L = 0.4 \Omega$ $I_D \cong 75 \text{ A}, \text{ V}_{GEN} = 10 \text{ V}, \text{ R}_g = 1 \Omega$		-	14	21	ns
Turn-Off Delay Time ^c	t _{d(off)}			-	34	51	
Fall Time ^c	t _f			-	9	14	
Source-Drain Diode Ratings and Characteristics b							
Pulsed Current ^a	I _{SM}			-	-	480	Α
Forward Voltage	V _{SD}	$I_F = 75 \text{ A}, V_{GS} = 0$		=	0.9	1.5	V

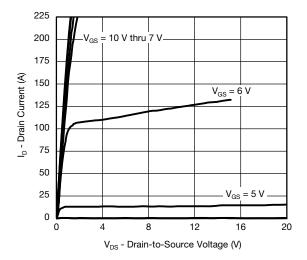
Notes

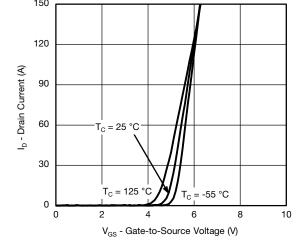
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



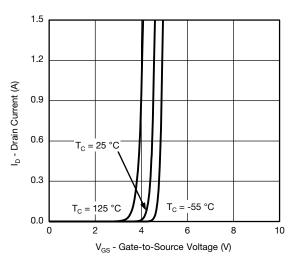
TYPICAL CHARACTERISTICS ($T_A = 25 \, ^{\circ}\text{C}$, unless otherwise noted)

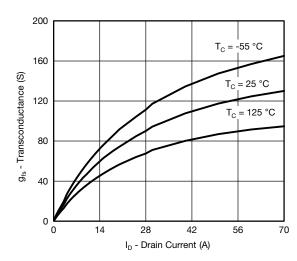




Output Characteristics

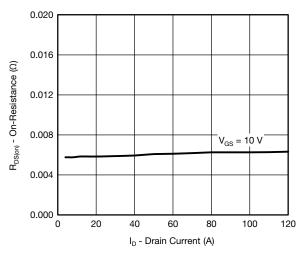
Transfer Characteristics

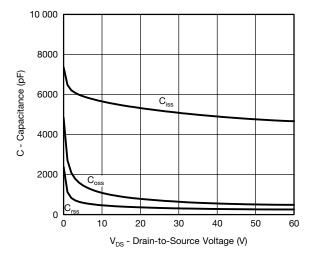




Transfer Characteristics

Transconductance



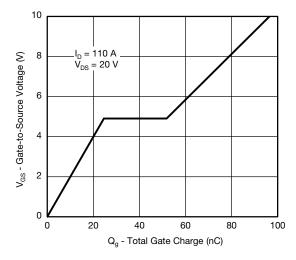


On-Resistance vs. Drain Current

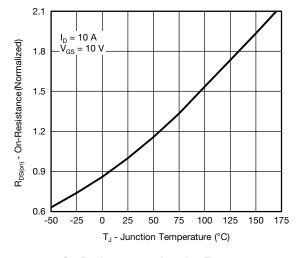
Capacitance



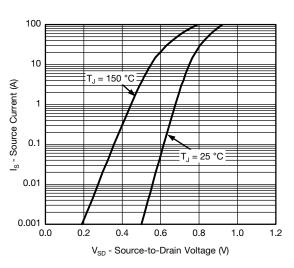
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



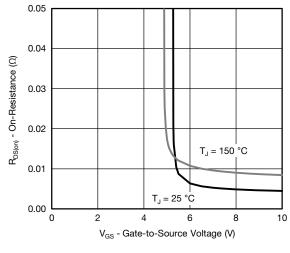
Gate Charge



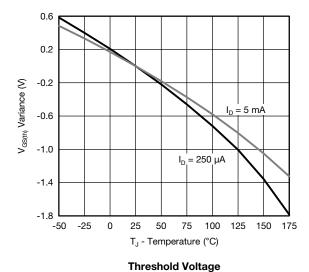
On-Resistance vs. Junction Temperature



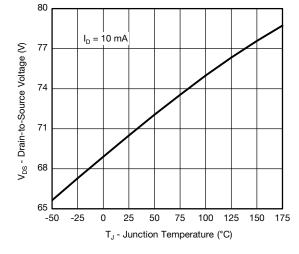
Source Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage



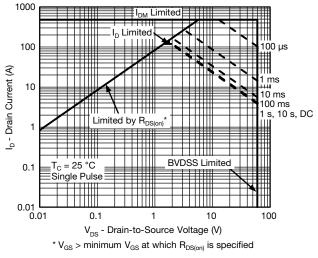
4



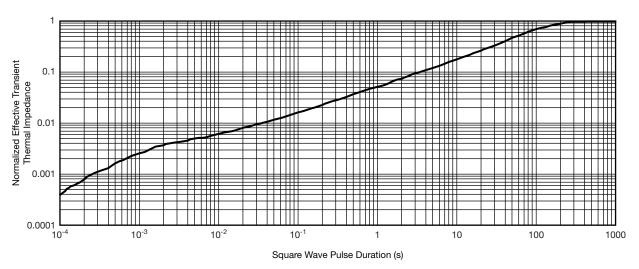
Drain Source Breakdown vs. Junction Temperature



THERMAL RATINGS ($T_A = 25$ °C, unless otherwise noted)



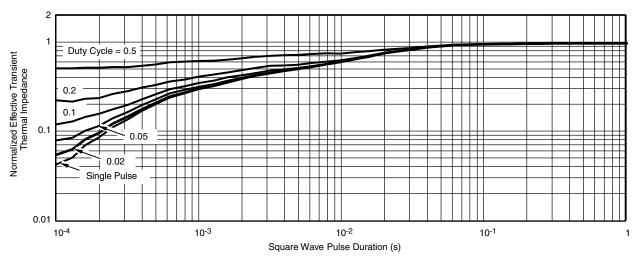
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



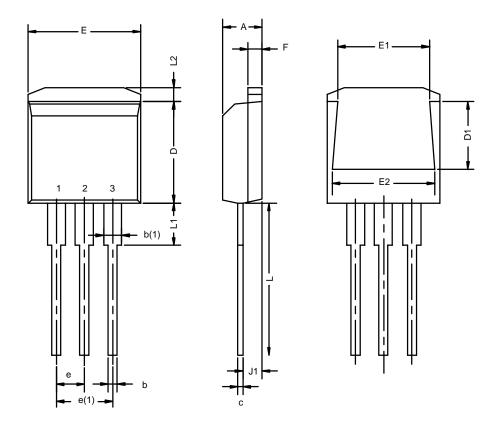
Normalized Thermal Transient Impedance, Junction-to-Case

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction-to-Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



TO-262: 3-LEAD



	MILLIM	ETERS*	INCHES		
Dim	Min	Max	Min	Max	
Α	4.32	4.70	0.170	0.185	
b	0.64	1.00	0.025	0.039	
b(1)	1.14	1.40	0.045	0.055	
С	0.36	0.50	0.014	0.020	
D	8.64	9.65	0.340	0.380	
D1	5.59	6.10	0.220	0.240	
е	2.41	2.67	0.095	0.105	
e(1)	4.95	5.33	0.195	0.210	
E	10.03	10.41	0.395	0.410	
E1	7.87	8.64	0.310	0.340	
E2	9.02	9.53	0.355	0.375	
F	1.14	1.40	0.045	0.055	
J1	2.41	2.79	0.095	0.110	
L	13.08	14.22	0.515	0.560	
L1	-	3.81	-	0.150	
L2	1.02	1.40	0.040	0.055	
ECN: T-02234—Rev. C, 14-Oct-02 DWG: 5855					

^{*}Use millimeters as the primary measurement



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